

# RFM8P08/8P10 RFP8P08/8P10

## P-Channel Enhancement-Mode Power Field-Effect Transistors

August 1991

### Features

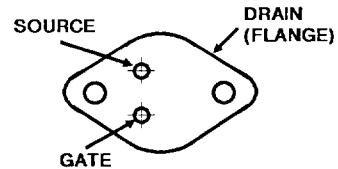
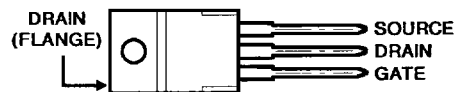
- -8A, -80V and -100V
- $r_{DS(on)} = 0.4\Omega$
- SOA is Power-Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device

### Description

The RFM8P08 and RFM8P10 and the RFP8P08 and RFP8P10 are p-channel enhancement-mode silicon gate power field-effect transistors designed for applications such as switching regulators, switching converters, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

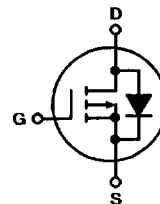
The RFM series types are supplied in the JEDEC TO-204AA steel package and the RFP series types in the JEDEC TO-220AB plastic package.

### Packages

 TO-204AA  
BOTTOM VIEW

 TO-220AB  
TOP VIEW


### Terminal Diagram

P-CHANNEL ENHANCEMENT MODE



### Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$ ) Unless Otherwise Specified

	RFM8P08	RFM8P10	RFP8P08	RFP8P10	UNITS	
Drain-Source Voltage .....	$V_{DS}$	-80	-100	-80	-100	V
Drain-Gate Voltage ( $R_{GS} = 1\text{ m}\Omega$ ) .....	$V_{DGR}$	-80	-100	-80	-100	V
Continuous Drain Current						
RMS Continuous .....	$I_D$	8	8	8	8	A
Pulsed Drain Current .....	$I_{DM}$	20	20	20	20	A
Gate-Source Voltage .....	$V_{GS}$	$\pm 20$	$\pm 20$	$\pm 20$	$\pm 20$	V
Maximum Power Dissipation						
$T_C = +25^\circ\text{C}$ .....	$P_D$	100	100	75	75	W
Above $T_C = +25^\circ\text{C}$ , Derate Linearly .....		0.8	0.8	0.6	0.6	W/ $^\circ\text{C}$
Operating and Storage Junction .....	$T_J, T_{STG}$	-55 to +150	-55 to +150	-55 to +150	-55 to +150	$^\circ\text{C}$
Temperature Range						

## Specifications RFM8P08, RFM8P10, RFP8P08, RFP8P10

**ELECTRICAL CHARACTERISTICS, At Case Temperature ( $T_c$ )=25°C unless otherwise specified.**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM8P08 RFP8P08		RFM8P10 RFP8P10		
			MIN.	MAX.	MIN.	MAX.	
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=1\text{ mA}$ $V_{GS}=0$	-80	—	-100	—	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}$ $I_D=1\text{ mA}$	-2	-4	-2	-4	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS}=-65\text{ V}$ $V_{DS}=-80\text{ V}$	—	1	—	—	$\mu\text{A}$
		$T_c=125^\circ\text{C}$ $V_{DS}=-65\text{ V}$ $V_{GS}=-80\text{ V}$	—	—	—	50	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20\text{ V}$ $V_{DS}=0$	—	100	—	100	nA
Drain-Source On Voltage	$V_{DS(on)}^a$	$I_D=4\text{ A}$ $V_{GS}=-10\text{ V}$	—	-1.6	—	-1.6	V
		$I_D=8\text{ A}$ $V_{GS}=-10\text{ V}$	—	-4.0	—	-4.0	
Static Drain-Source On Resistance	$r_{DS(on)}^a$	$I_D=4\text{ A}$ $V_{GS}=-10\text{ V}$	—	.4	—	.4	$\Omega$
Forward Transconductance	$g_{fs}^a$	$V_{DS}=10\text{ V}$ $I_D=4\text{ A}$	2	—	2	—	mho
Input Capacitance	$C_{iss}$	$V_{DS}=25\text{ V}$	—	1500	—	1500	pF
Output Capacitance	$C_{oss}$	$V_{GS}=0\text{ V}$	—	700	—	700	
Reverse Transfer Capacitance	$C_{rss}$	$f = 1\text{ MHz}$	—	300	—	300	
Turn-On Delay Time	$t_d(on)$	$V_{DD} = 50\text{ V}$ $I_D=4\text{ A}$ $R_{\theta en}=R_{\theta gs}=50\ \Omega$	18(typ)	60	18(typ)	60	ns
Rise Time	$t_r$		70(typ)	150	70(typ)	150	
Turn-Off Delay Time	$t_d(off)$		166(typ)	275	166(typ)	275	
Fall Time	$t_f$		94(typ)	175	94(typ)	175	
Thermal Resistance Junction-to-Case	$R\theta_{jc}$	RFM8P08, RFM8P10	—	1.25	—	1.25	$^\circ\text{C/W}$
		RFP8P08, RFP8P10	—	1.67	—	1.67	

<sup>a</sup>Pulsed: Pulse duration = 300  $\mu\text{s}$  max., duty cycle = 2%.

### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFM8P08 RFP8P08		RFM8P10 RFP8P10		
			Min.	Max.	Min.	Max.	
Diode Forward Voltage	$V_{SD}$	$I_{SD} = 4\text{ A}$	—	1.4	—	1.4	V
Reverse Recovery Time	$t_{rr}$	$I_F = 4\text{ A}$ $d_I/d_t = 100\text{ A}/\mu\text{s}$	200(typ.)		200(typ.)		ns

\*Pulse Test: Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

**5**  
**P-CHANNEL  
POWER MOSFETS**

RFM8P08, RFM8P10, RFP8P08, RFP8P10

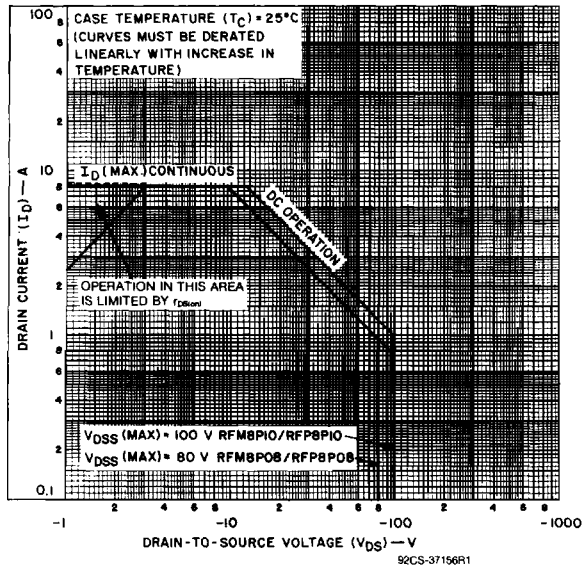


Fig. 1 — Maximum operating areas for all types.

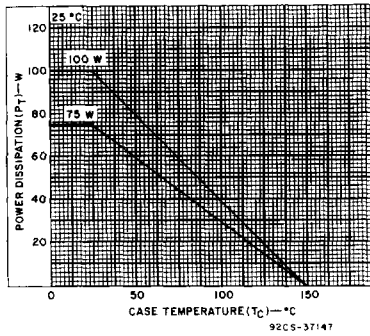


Fig. 2 — Power dissipation vs. case temperature derating curve for all types.

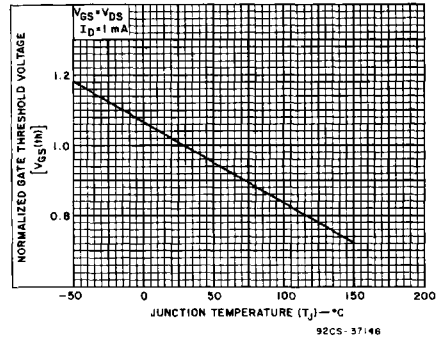


Fig. 3 — Typical normalized gate threshold voltage as a function of junction temperature for all types.

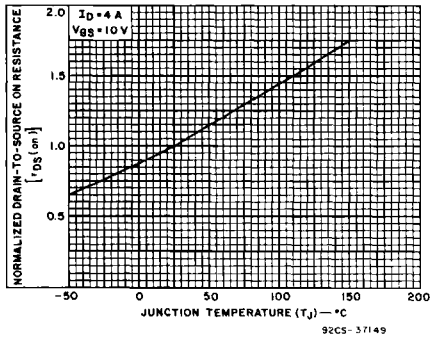


Fig. 4 — Normalized drain-to-source on resistance to junction temperature for all types.

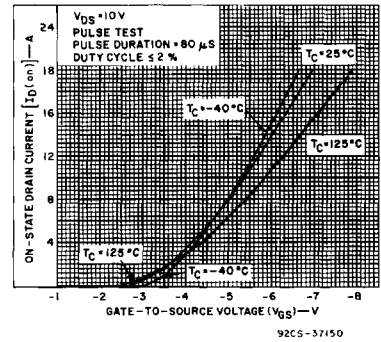


Fig. 5 — Typical transfer characteristics for all types.

# RFM8P08, RFM8P10, RFP8P08, RFP8P10

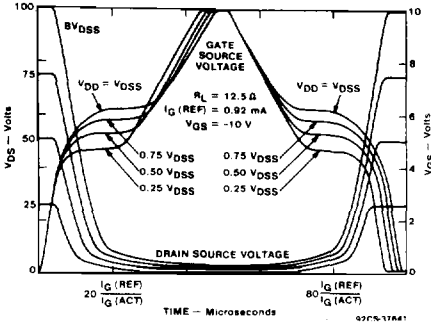


Fig. 6 - Normalized switching waveforms for constant gate-current. Refer to Harris application notes AN-7254 and AN-7260.

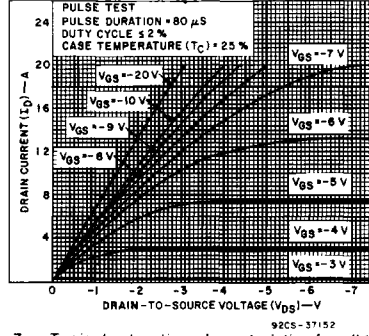


Fig. 7 - Typical saturation characteristics for all types.

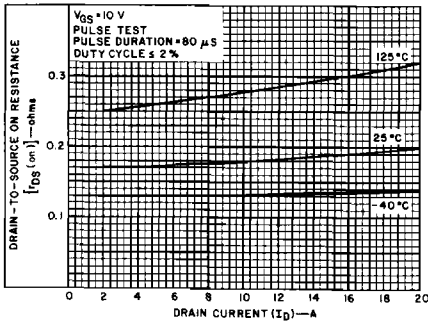


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

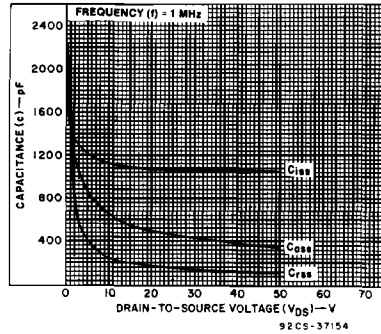


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

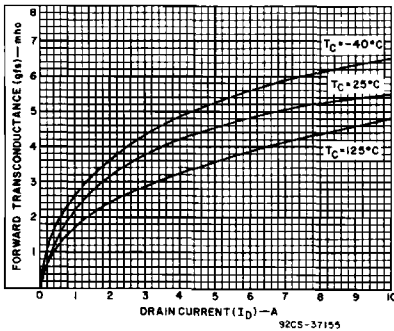


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

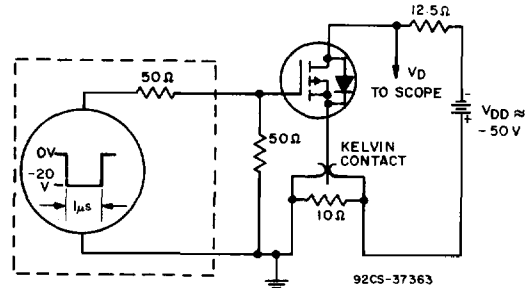


Fig. 11 - Switching Time Test Circuit.